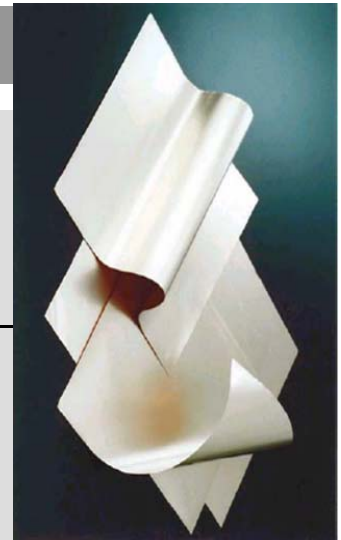


Standard size warp weft mm	Polyimide film thickness	Copper foil type	Copper foil thickness
			9 $\mu$ m
700 x 510		Rolled	12 $\mu$ m
1050 x 510	20 $\mu$ m		18 $\mu$ m
1100 x 510	25 $\mu$ m		35 $\mu$ m
1250 x 510	35 $\mu$ m		
roll x 250	50 $\mu$ m	Electro- deposited	9 $\mu$ m
roll x 500			12 $\mu$ m
			18 $\mu$ m



Other thicknesses on request

## [ Features ]

- ▶ Flexible copper clad laminates based on polyimide film
- ▶ Adhesiveless type due to laminate method
- ▶ High solder heat resistance achieved through low water absorption
- ▶ High copper-foil peel strength, dimensional stability and flexibility
- ▶ Single side clad version R-F770 available
- ▶ On request: R-F785 / R-F780 thin PI 14  $\mu$ m and 25  $\mu$ m  
R-F551 / R-F552 single side clad (casting method)  
Coverlayer (halogenfree) R - CAES

## [ Applications ]

Hing part of cellular phone and PDA, liquid cristal driver, optical pick-up drive part, camera part in cellular phone, digital video camera, digital camera, etc